

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"6607955".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 14:33
L2	65833	CMP or "chemical mechanical polishing"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 14:34
L3	65	polysilicon same (oxide or dielectric) same ("H.sub.2O.sub.2" or "hygrogen peroxide")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 14:38
L4	114	polysilicon and (oxide or dielectric) and ("H.sub.2O.sub.2" or "hygrogen peroxide") and slurry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 14:59
L5	0	4 and 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 14:38
L6	89	4 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 14:38
L7	62	polysilicon and ("H.sub.2O.sub.2" or "hygrogen peroxide") and slurry and pH	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 15:41
L8	116	polysilicon and ("H.sub.2O.sub.2" or "hygrogen peroxide") and slurry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 15:59

L9	76	("H.sub.2O.sub.2" or "hydrogen peroxide") same slurry same oxidizer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 15:59
L10	396	("H.sub.2O.sub.2" or "hydrogen peroxide") same slurry	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 16:04
L11	35	polysilicon and 10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/26 15:59